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**MAR 22 2007**

**Integrated chip package structure using organic substrate and method of  
manufacturing the same**

Appl. No. : 10/055,499 Confirmation No. 7456  
Applicant : Jin-Yuan Lee,  
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Filed : January 22, 2002  
TC/A.U. : 2891  
Examiner : THAI, LUAN C  
Docket No. : MEGP0012USA  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT**

5 Sir:

The Restriction Requirement mailed Feb. 23, 2007 has been carefully considered. In response thereto, please enter the following amendments as follows and consider the following remarks:

10 Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.  
Remarks/Arguments begin on page 15 of this paper.